LIST OF REFERENCES CITED BY APPLICANT *(Use several sheets if necessary)*	ATTY. DOCKET NO. 100665.0053US1	SERIAL NO. 10/[illegible],942
	APPLICANT Jesse Pedigo, et al.	
	FILING DATE 01/03/02	GROUP TC 1700

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*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
YS		3,601,523	08/24/71	Through Hole Connectors	174	68.5	06/19/70
YS		4,106,187	08/15/78	Curved Rigid Printed Circuit Boards	29	625	01/16/76
YS		4,283,243	08/11/81	Use of Photosensitive Stratum to Create Through-Hole Connections in Circuit Boards	156	237	03/20/80
YS		4,360,570	11/23/82	Use of Photosensitive Stratum to Create Through-Hole Connections in Circuit Boards	428	596	06/15/81
YS		4,622,239	11/11/86	Method and Apparatus for Dispensing Viscous Materials	427	96	02/18/86
YS		4,700,474	10/20/87	Apparatus and Method for Temporarily Sealing Holes in Printed Circuit Boards	29	846	11/26/86
YS		4,777,721	10/18/88	Apparatus and Method for Temporarily Sealing Holes in Printed Circuit Boards Utilizing a Thermodeformable Material	29	846	10/15/87
YS		4,783,247	11/8/88	Method and Manufacture for Electrically Insulating Base Material Used in Plated-Through Printed Circuit Panels	204	181.1	05/15/86
YS		4,884,337	12/05/89	Method for Temporarily Sealing Holes in Printed Circuit Boards Utilizing a Thermodeformable Material	29	846	10/15/87
YS		4,954,313	09/04/90	Method and Apparatus for Filling High Density Vias	419	9	02/03/89
YS		4,964,948	10/23/90	Printed Circuit Board Through Hole Technique	156	659	11/13/89
YS		4,995,941	02/26/91	Method of Manufacture Interconnect Device	156	630	05/15/89
YS		5,053,921	10/01/91	Multilayer Interconnect Device and Method of Manufacture Thereof	361	386	10/23/90
YS		5,058,265	10/22/91	Method for Packaging a Board of Electronic Components	29	852	09/10/90
YS		5,117,069	05/26/92	Circuit Board Fabrication	174	261	09/28/90
YS		5,133,120	07/28/92	Method of Filling Conductive Material into Through Holes of Printed Wiring Board	29	852	03/15/91
YS		5,145,691	09/08/92	Apparatus for Packing Filler into Through-Holes or the Like in a Printed Circuit Board	425	110	03/22/91
YS		5,220,723	06/22/93	Process for Preparing Multi-Layer Printed Wiring Board	29	830	11/04/91
YS		5,274,916	01/04/94	Method of Manufacturing Ceramic Multilayer Electronic Component	29	848	12/17/92

ATTY. DOCKET NO.	SERIAL NO.
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Jesse Pedigo, et al.	
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*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
YS		5,851,344	12/22/98	Ultrasonic Wave Assisted Contact Hole Filling	156	379.6	12/22/98
YS		5,906,042	05/25/99	Method and Structure to Interconnect Traces of Two Conductive Layers in a Printed Circuit Board	29	852	10/04/95
YS		5,925,414	07/20/99	Nozzle and Method for Extruding Conductive Paste into High Aspect Ratio Openings	427	282	07/20/99
YS		5,994,779	11/30/99	Semiconductor Fabrication Employing a Spacer Metallization Technique	257	773	05/02/97
YS		6,000,129	12/14/99	Process for Manufacturing a Circuit with Filled Holes	29	852	03/12/98
YS		6,009,620	01/04/00	Method of Making a Printed Circuit Board Having Filled Holes	29	852	07/15/98
YS		6,079,100	06/27/00	Method of Making a Printed Circuit Board Having Filled Holes and Fill Member for Use Therewith	29	852	05/12/98
YS		6,090,474	07/18/00	Flowable Compositions and Use in Filling Vias and Plated Through-Holes	428	209	07/18/00
YS		6,015,520	01/18/00	Method for Filling Holes in Printed Wiring Boards	264	104	05/15/97
YS		6,106,891	08/22/00	Via Fill Compositions for Direct Attach of Devices and Method for Applying Same	427	97	12/18/98
YS		6,138,350	10/31/00	Process for Manufacturing a Circuit Board with Filled Holes	29	852	02/25/98
YS		6,149,857	11/21/00	Method of Making Films and Coatings Having Anisotropic Conductive Pathways Therein	264	429	12/22/98
YS		6,153,508	11/28/00	Multi-Layer Circuit Having a Via Matrix Interlayer Connection and Method for Fabricating the Same	438	622	02/19/98
YS		6,184,133	02/06/01	Method of Forming an Assembly Board with Insulator Filled Through Holes	438	667	02/18/00
YS		6,261,501	07/17/01	Resin Sealing Method for A Semiconductor Device	264	272.15	01/22/99
YS		6,276,055	08/21/01	Method and Apparatus for Forming Plugs in Vias of a Circuit Board Layer	29	852	09/24/98
YS		6,281,448	08/28/01	Printed Circuit Board and Electronic Components	174	260	08/10/99
YS		6,282,782	09/04/01	Forming Plugs in Vias of Circuit Board Layers and Subassemblies	29	852	09/02/99

YS		5,277,854	01/11/94	Methods and Apparatus for Making Grids from Fibers	264	86	06/06/91
YS		5,332,439	07/26/94	Screen Printing Apparatus for Filling Through-Holes in Circuit Board with Paste	118	213	08/18/92
YS		5,540,779	07/30/96	Apparatus for Manufacture of Multi-Layer Ceramic Interconnect Structures	118	692	03/01/95
YS		5,766,670	06/16/98	Via Fill Compositions for Direct Attach of Devices and Methods for Applying Same	427	8	11/17/93
YS		5,578,151	11/26/96	Manufacture of A Multi-Layer Interconnect Structure	156	64	03/01/95
YS		5,591,353	01/07/97	Reduction of Surface Copper Thickness on Surface Mount Printed Wire Boards with Copper Plated Through Holes by the Chemical Planarization Method	216	18	08/18/94
YS		5,610,103	03/11/97	Ultrasonic Wave Assisted Contact Hole Filling	437	225	12/12/95
YS		5,637,834	06/10/97	Multilayer Circuit Substrate and Method for Forming Same	174	264	02/03/95
YS		5,662,987	09/02/97	Multilayer Printed Wiring Board and Method of Making Same	428	209	02/01/96
YS		5,699,613	12/23/97	Fine Dimension Stacked Vias for a Multiple Layer Circuit Board Structure	29	852	09/25/95
YS		5,707,575	01/13/98	Method for Filling Vias in Ceramic Substrates with Composite Metallic Paste	264	104	07/28/94
YS		5,744,171	04/28/98	System for Fabricating Conductive Epoxy Grid Array Semiconductor Packages	425	110	05/12/97
YS		5,744,285	04/28/98	Composition and Process for Filling Vias	430	318	07/18/96
YS		5,753,976	05/19/98	Multi-Layer Circuit Having a Via Matrix Interlayer Connection	257	774	06/14/96
YS		5,761,803	06/09/98	Method of Forming Plugs in Vias of A Circuit Board by Utilizing a Porous Membrane	29	852	06/26/96
YS		5,766,670,	06/16/98	Via Fill Compositions for Direct Attach of Devices and Methods for Applying Same	427	8	11/17/93
YS		5,822,856	10/20/98	Manufacturing Circuit Boards Assemblies Having Filled Vias	29	832	06/28/96
YS		5,824,155	10/20/98	Method and Apparatus for Dispensing Viscous Material	118	410	11/08/95

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		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	TRANSLATION NO

OTHER REFERENCES (*Including Author, Title, Date, Pertinent Pages, Etc.*)

EXAMINER	DATE CONSIDERED
Yuriy Semenenko	02/24/2005

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LIST OF REFERENCES CITED BY APPLICANT *(Use several sheets if necessary)*	ATTY. DOCKET NO. 100665.0053US1	SERIAL NO. 10/039,942
	APPLICANT Jesse Pedigo, et al.	
	FILING DATE January 3, 2002	GROUP 1725

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*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
YS		5,277,854	01/11/94	Hunt	264	86	06/06/91
YS		5,451,721	09/19/95	Tsukada, et al.	174	261	09/24/91
YS		5,456,004	10/10/95	Swamy	29	882	01/04/94
YS		5,471,091	11/28/95	Pasch, et al.	257	752	08/26/91
YS		5,532,516	07/02/96	Pasch, et al.	257	752	03/28/95
YS		5,753,976	05/19/98	Harvey	257	774	06/14/96

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YS		WO 00/13474						

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EXAMINER	Yuriy Semenenko	DATE CONSIDERED	12/09/2004

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		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	TRANSLATION NO
YS		EP 0 194 247 A2					V	
YS		EP 0 713 358 A2					V	
YS		EP 0 723 388 A1					V	
YS		GB 2 120 017 A					V	
YS		GB 2 341 347 A					V	
YS		GB 2 246 912 A					V	
YS		JP 04239193					V	
YS		JP 05275819					V	
YS		JP 53-104857						V
YS		JP 54-139065						V
YS		JP 62-277794						V
YS		JP 62-287696						V
YS		JP 03004595					V	
YS		JP 04186792					V	
YS		JP 07176871					V	
YS		JP 08172265					V	
YS		JP 08191184					V	
YS		JP 09321399					V	
YS		JP 09083135					V	
YS		JP 10065339					V	
YS		JP 10256687					V	
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YS		JP 1173696					V	
YS		JP 1236694						V
YS		JP 58011172					V	
YS		FR 2 684 836						V

YS		FR 2 714 567						V	
YS		WO 86/06243						V	

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YS		Via Etching Process, February 1972
YS		Multilayer Printed Circuit Board Connections, April 1996
YS		Process for Forming Copper Clad Vias, August 1989

EXAMINER	DATE CONSIDERED
Yuriy [illegible]	02/25/2005

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